

CLAIM AMENDMENTS

1. (Original) A system for reducing apparent height of a board system, comprising:

a carrier;

a component mounted on a first side of the carrier;

a printed circuit board with a hole, the hole being structured to accommodate the component; and

a solder material soldering the carrier to the printed circuit board and providing a structural bond between the carrier and the printed circuit board, at least one portion of the solder material providing an electrical coupling between the carrier and the printed circuit board,

wherein at least one portion of the component is maintained in the hole after the carrier is soldered to the printed circuit board.

2. (Original) The system according to claim 1, further comprising a paste material disposed between the component and the first side of the carrier.

3. (Original) The system according to claim 2, wherein the paste material is adapted to provide a bond between the component and the carrier and is adapted to provide an electrical coupling between the component and the carrier.

4. (Original) The system according to claim 3,
wherein the carrier includes a printed circuit printed on at least the first side of the carrier, and

wherein the paste material is adapted to provide an electrical coupling between the printed circuit of the carrier and the component.

5. (Original) The system according to claim 4, wherein the component is electrically coupled to the printed circuit board via the paste material, the printed circuit of the carrier and the solder material.

6. (Original) The system according to claim 3, wherein the paste material has a higher melting temperature than the solder material.

7. (Original) The system according to claim 1, wherein the solder material provides the only electrical coupling between the carrier and the printed circuit board.

8. (Original) The system according to claim 1, wherein the solder material provides the only structural bond between the carrier and the printed circuit board.

9. (Original) A wireless communications device, comprising:
a duplexer;
a carrier board having a first side on which is mounted the duplexer;
a printed circuit board with a hole through which the duplexer fits; and
a solder material soldering the carrier board to the printed circuit board
and providing a structural bond between the carrier board and the printed circuit board, at least one portion of the solder material providing an electrical coupling between the carrier board and the printed circuit board,

wherein the duplexer is coupled electrically to printed circuit board via the carrier board and the at least one portion of the solder material.

10. (Original) A computer system, comprising:
a printed circuit board;
a packaged integrated chip;

a carrier having a first side on which the packaged integrated chip is mounted;

a printed circuit board with a hole through which the packaged integrated chip fits; and

a solder material soldering the carrier to the printed circuit board and providing a structural bond between the carrier and the printed circuit board, at least one portion of the solder material providing an electrical coupling between the carrier and the printed circuit board,

wherein the packaged integrated chip is coupled electrically to printed circuit board via the carrier board and the at least one portion of the solder material.

11. (Canceled)

12. (Canceled)

13. (Canceled)

14. (Canceled)

15. (Canceled)

16. (Canceled)

17. (Canceled)

18. (Canceled)

19. (Canceled)

20. (New) The system according to claim 1 wherein the carrier is integrally formed with the component.
21. (New) The system according to claim 20, wherein the carrier is a portion of the component, and includes a lateral protrusion.
22. (New) The system according to claim 1, wherein the hole extends through the printed circuit board.
23. (New) The system according to claim 1, wherein the hole does not extend through the printed circuit board and forms a recess in the printed circuit board, the bottom of the recess receiving the carrier.
24. (New) The system according to claim 23 wherein the carrier is integrally formed with the component.